

2.5-V 460-kbps RS-232 TRANSCEIVER WITH ± 15 -kV ESD PROTECTION

Check for Samples: [TRS3318E](#)

FEATURES

- **ESD Protection for RS-232 I/O Pins**
 - ± 15 kV (Human-Body Model)
 - ± 8 kV (IEC 61000-4-2, Contact Discharge)
 - ± 15 kV (IEC 61000-4-2, Air-Gap Discharge)
- **300- μ A Operating Supply Current**
- **1- μ A Low-Power Standby Mode (With Receivers Active)**
- **Designed to Transmit at a Data Rate of 460 kbps**
- **Auto-Powerdown Plus Option Features Flexible Power-Saving Mode**
- **Operates From a Single 2.25-V to 3-V V_{CC} Supply**
- **Designed to be Interchangeable With Industry Standard '3318 Devices**

APPLICATIONS

- **Battery-Powered Systems**
- **PDA's**
- **Cellular Phones**
- **Notebooks**
- **Hand-Held Equipment**
- **Pagers**

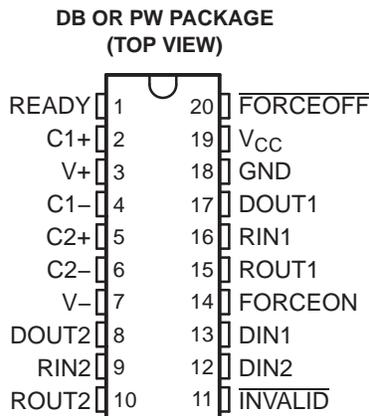
DESCRIPTION

The TRS3318E is a dual-driver, dual-receiver, RS-232-compatible transceiver. The device features auto-powerdown plus and enhanced electrostatic discharge (ESD) protection integrated into the chip. Driver output and receiver input are protected to ± 15 kV using the IEC 61000-4-2 Air-Gap Discharge method, ± 8 kV using the IEC 61000-4-2 Contact Discharge method, and ± 15 kV using the Human-Body Model (HBM).

The device operates at a data rate of 460 kbps. The transceiver has a proprietary low-dropout driver output stage, enabling RS-232-compatible operation from a 2.25-V to 3-V supply with a dual charge pump. The charge pump requires only four 0.1- μ F capacitors and features a logic-level output (READY) that asserts when the charge pump is regulating and the device is ready to begin transmitting.

The TRS3318E achieves a 1- μ A supply current using the auto-powerdown feature. This device automatically enters a low-power power-down mode when the RS-232 cable is disconnected or the drivers of the connected peripherals are inactive for more than 30 s. The device turns on again when it senses a valid transition at any driver or receiver input. Auto-powerdown saves power without changes to the existing BIOS or operating system.

This device is available in two space-saving packages: 20-pin SSOP and 20-pin TSSOP.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

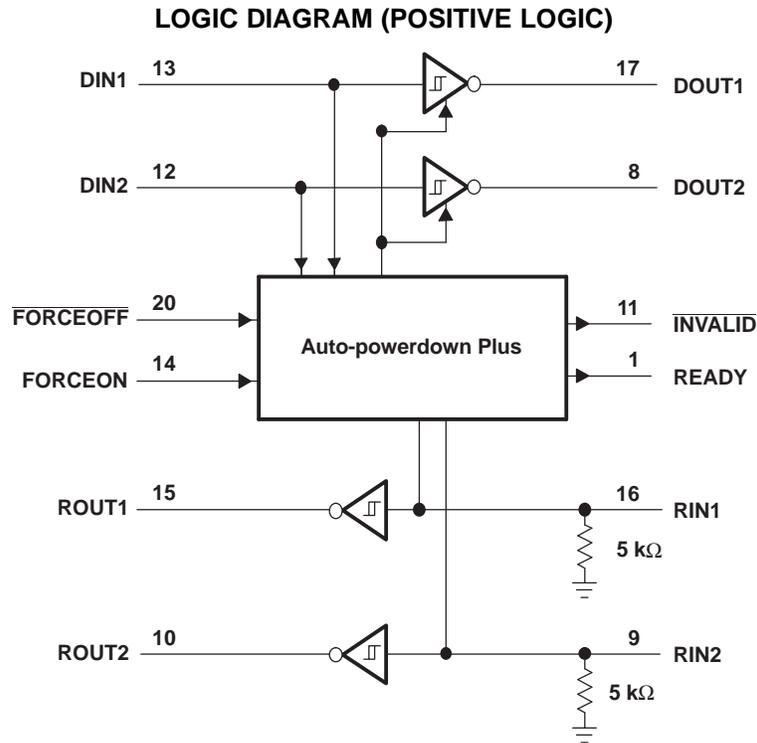
DETAILED DESCRIPTION

Flexible control options for power management are featured when the serial port and driver inputs are inactive. The auto-powerdown plus feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense valid signal transitions on all receiver and driver inputs for approximately 30 s, the built-in charge pump and drivers are powered down, reducing the supply current to 1 μ A. By disconnecting the serial port or placing the peripheral drivers off, auto-powerdown plus can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown plus enabled, the device activates automatically when a valid signal is applied to any receiver or driver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than -2.7 V, or has been between -0.3 V and 0.3 V for less than 30 μ s (typical number). INVALID is low (invalid data) if all receiver input voltage are between -0.3 V and 0.3 V for more than 30 μ s (typical number).

FUNCTION TABLE⁽¹⁾

| INPUT CONDITIONS | | | | OUTPUT STATES | | | | OPERATING MODE |
|---------------------------------------|----------|-------------------------------------|--|---------------|----------|---------|-------|--|
| FORCEON | FORCEOFF | RECEIVER OR DRIVER EDGE WITHIN 30 s | VALID RS-232 LEVEL PRESENT AT RECEIVER | DRIVER | RECEIVER | INVALID | READY | |
| Auto-Powerdown Plus Conditions | | | | | | | | |
| H | H | No | No | Active | Active | L | H | Normal operation, auto-powerdown plus disabled |
| H | H | No | Yes | Active | Active | H | H | Normal operation, auto-powerdown plus disabled |
| L | H | Yes | No | Active | Active | L | H | Normal operation, auto-powerdown plus enabled |
| L | H | Yes | Yes | Active | Active | H | H | Normal operation, auto-powerdown plus enabled |
| L | H | No | No | Z | Active | L | L | Power down, auto-powerdown plus enabled |
| L | H | No | Yes | Z | Active | H | L | Power down, auto-powerdown plus enabled |
| X | L | X | No | Z | Active | L | L | Manual power down |
| X | L | X | Yes | Z | Active | H | L | Manual power down |
| Auto-Powerdown Conditions | | | | | | | | |
| INVALID | INVALID | X | No | Z | Active | L | L | Power down, auto-powerdown enabled |
| INVALID | INVALID | X | Yes | Active | Active | H | H | Normal operation, auto-powerdown enabled |

(1) H = high level, L = low level, X = irrelevant, Z = high impedance



TERMINAL FUNCTIONS

| TERMINAL | | DESCRIPTION |
|------------------------------|--------|--|
| NAME | NO. | |
| C1+ | 2 | Positive voltage-doubler charge-pump capacitor |
| C1– | 4 | Negative voltage-doubler charge-pump capacitor |
| C2+ | 5 | Positive inverting charge-pump capacitor |
| C2– | 6 | Negative inverting charge-pump capacitor |
| DIN | 12, 13 | CMOS driver inputs |
| DOUT | 8, 17 | RS-232 driver outputs |
| $\overline{\text{FORCEOFF}}$ | 20 | Force-off input, active low. Drive low to power down transmitters and charge pump. This overrides auto-powerdown and FORCEON (see Function Table). |
| FORCEON | 14 | Force-on input, active high. Drive high to override auto-powerdown, keeping transmitters on ($\overline{\text{FORCEOFF}}$ must be high) (see Function Table). |
| GND | 18 | Ground |
| $\overline{\text{INVALID}}$ | 11 | Valid signal detector output, active low. A logic high indicates that a valid RS-232 level is present on a receiver input. |
| READY | 1 | Ready to transmit output, active high. READY is enabled high when V– goes below –3.5 V and the device is ready to transmit. |
| RIN | 9, 16 | RS-232 receiver inputs |
| ROUT | 10, 15 | CMOS receiver outputs |
| V+ | 3 | $2 \times V_{\text{CC}}$ generated by the charge pump |
| V– | 7 | $-2 \times V_{\text{CC}}$ generated by the charge pump |
| V _{CC} | 19 | 2.25-V to 3-V single-supply voltage |

Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | MIN | MAX | UNIT |
|--|--|------|-----------------------|------|
| V _{CC} to GND | | -0.3 | 6 | V |
| V ₊ to GND ⁽²⁾ | | -0.3 | 7 | V |
| V ₋ to GND ⁽²⁾ | | -7 | 0.3 | V |
| V ₊ + V ₋ ⁽²⁾ | | | 13 | V |
| Input voltage | DIN, FORCEON, FORCEOFF to GND | -0.3 | 6 | V |
| | RIN to GND | | ±25 | |
| Output voltage | DOUT to GND | | ±13.2 | V |
| | ROUT, INVALID, READY to GND | -0.3 | V _{CC} + 0.3 | |
| Short-circuit duration | DOUT to GND | | Continuous | |
| Continuous power dissipation (T _A = 70°C) | 20-pin SSOP (derate 8 mW/°C above 70°C) | | 640 | mW |
| | 20-pin TSSOP (derate 7 mW/°C above 70°C) | | 559 | |
| Storage temperature range | | -65 | 150 | °C |
| Lead temperature (soldering, 10 s) | | | 300 | °C |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) V₊ and V₋ can have maximum magnitudes of 7 V, but their absolute difference cannot exceed 13 V.

Recommended Operating Conditions

See Figure 4

| | | | MIN | NOM | MAX | UNIT |
|-----------------|---|--|-----------------------|-----------------------|-----|------|
| Supply voltage | | | 2.25 | 2.5 | 3 | V |
| V _{IH} | Driver and control high-level input voltage | DIN, FORCEOFF, FORCEON V _{CC} = 2.5 V to 3 V | 0.7 × V _{CC} | | 5.5 | V |
| V _{IL} | Driver and control low-level input voltage | DIN, FORCEOFF, FORCEON V _{CC} = 2.5 V to 3 V | 0 | 0.3 × V _{CC} | | V |
| V _I | Receiver input voltage | | -25 | 25 | | V |
| T _A | Operating free-air temperature | TRS3318EC | 0 | | 70 | °C |
| | | TRS3318EI | -40 | | 85 | |

Supply Current Section

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25\text{ V to }3\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$, $T_A = T_{MIN}\text{ to }T_{MAX}$ (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|---|---|-----|--------------------|-----|---------------|
| DC Characteristics ($V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$) | | | | | |
| Auto-powerdown plus supply current | FORCEON = GND, $\overline{\text{FORCEOFF}} = V_{CC}$, All RIN and DIN idle | | 1 | 10 | μA |
| Auto-powerdown supply current | $\overline{\text{FORCEOFF}} = \text{GND}$ | | 1 | 10 | μA |
| Supply current | FORCEON = $\overline{\text{FORCEOFF}} = V_{CC}$, No load | | 0.3 | 2 | mA |

(1) Typical values are at $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$.

ESD Protection

| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|-----------|--|----------|------|
| RIN, DOUT | HBM | ± 15 | kV |
| | IEC 61000-4-2 Air-Gap Discharge method | ± 15 | |
| | IEC 61000-4-2 Contact Discharge method | ± 8 | |

Driver Section

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature, $V_{CC} = 2.25\text{ V to }3\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see [Figure 4](#))

| PARAMETER | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|---|---|-----------|--------------------|----------|---------------|
| Driver input hysteresis | | | 0.3 | | V |
| Input leakage current | FORCEON, DIN, FORCEOFF | | ± 0.01 | ± 1 | μA |
| Output voltage swing | All driver outputs loaded with 3 k Ω to ground | ± 3.7 | ± 4 | | V |
| Output resistance | $V_{CC} = 0$, Driver output = $\pm 2\text{ V}$ | 300 | 10M | | Ω |
| Output short-circuit current ⁽²⁾ | | | ± 25 | ± 60 | mA |
| Output leakage current | $V_{CC} = 0$ or 2.25 V to 3 V, $V_{OUT} = \pm 12\text{ V}$, Drivers disabled | | | ± 25 | μA |

(1) Typical values are at $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Short-circuit durations should be controlled to prevent exceeding the device absolute power dissipation ratings, and not more than one output should be shorted at a time.

Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature, $V_{CC} = 2.25\text{ V to }3\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see [Figure 1](#))

| PARAMETER | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|--|--|-----|--------------------|-----|------------------|
| Maximum data rate | $R_L = 3\text{ k}\Omega$, $C_L = 1000\text{ pF}$, One transmitter switching | 460 | | | kbps |
| $ t_{PHL} - t_{PLH} $ Driver skew ⁽²⁾ | | | 100 | | ns |
| Transition-region slew rate | $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$, $R_L = 3\text{ k}\Omega$ to 7 k Ω , Measured from 3 V to -3 V or -3 V to 3 V, $C_L = 150\text{ pF}$ to 2500 pF | 4 | | 30 | V/ μs |

(1) Typical values are at $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

Receiver Section

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25\text{ V to }3\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see [Figure 4](#))

| PARAMETER | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|------------------------|----------------------------|---------------------|--------------------|---------------------|---------------|
| Input voltage range | | -25 | | 25 | V |
| Input threshold low | $T_A = 25^\circ\text{C}$ | | | $0.3 \times V_{CC}$ | V |
| Input threshold high | $T_A = 25^\circ\text{C}$ | $0.7 \times V_{CC}$ | | | V |
| Input hysteresis | | | 0.3 | | V |
| Input resistance | $T_A = 25^\circ\text{C}$ | 3 | 5 | 7 | k Ω |
| Output leakage current | | | ± 0.05 | ± 10 | μA |
| Output voltage low | $I_{OUT} = 0.5\text{ mA}$ | | | $0.1 \times V_{CC}$ | V |
| Output voltage high | $I_{OUT} = -0.5\text{ mA}$ | $0.9 \times V_{CC}$ | | | V |

(1) Typical values are at $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$.

Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature,
 $V_{CC} = 2.25\text{ V to }3\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$ (unless otherwise noted) (see [Figure 4](#))

| PARAMETER | TEST CONDITIONS | TYP ⁽¹⁾ | UNIT |
|-----------------------|--|--------------------|---------------|
| t_{PHL} | Receiver propagation delay RIN to ROUT, $C_L = 150\text{ pF}$ | 0.175 | μs |
| t_{PLH} | | 0.175 | |
| $ t_{PHL} - t_{PLH} $ | Receiver skew ⁽²⁾ | 50 | ns |

(1) Typical values are at $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$.

(2) Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

Auto-Powerdown Plus Section

Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature, $V_{CC} = 2.25\text{ V to }3\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see [Figure 4](#))

| PARAMETER | TEST CONDITIONS | MIN | MAX | UNIT |
|--|----------------------------|---------------------|---------------------|------|
| Receiver input threshold to $\overline{\text{INVALID}}$ high | Positive threshold | | 2.7 | V |
| | Negative threshold | -2.7 | | |
| Receiver input threshold $\overline{\text{INVALID}}$ low | | -0.3 | 0.3 | V |
| $\overline{\text{INVALID}}$, READY voltage low | $I_{OUT} = 0.5\text{ mA}$ | | $0.1 \times V_{CC}$ | V |
| $\overline{\text{INVALID}}$, READY voltage high | $I_{OUT} = -0.5\text{ mA}$ | $0.8 \times V_{CC}$ | | V |

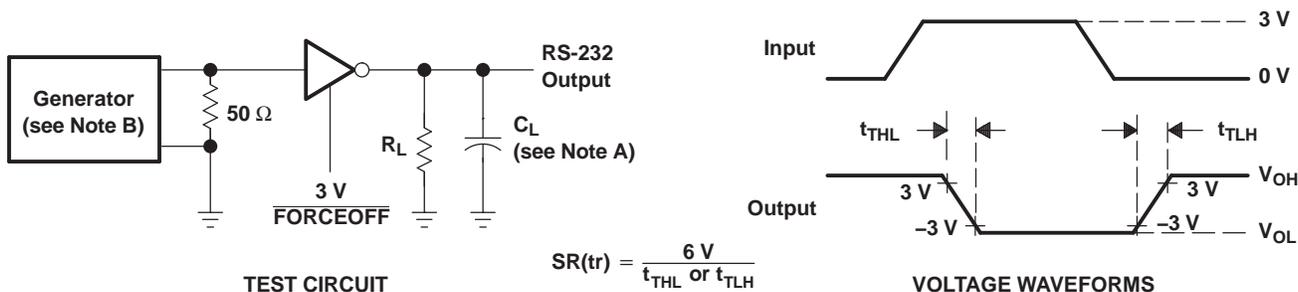
Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature, $V_{CC} = 2.25\text{ V to }3\text{ V}$, $C1\text{--}C4 = 0.1\text{ }\mu\text{F}$, $T_A = T_{MIN}$ to T_{MAX} (unless otherwise noted) (see [Figure 4](#))

| PARAMETER | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT |
|--|-------------------------|-----|--------------------|-----|---------------|
| t_{INVH} Receiver positive or negative threshold to $\overline{\text{INVALID}}$ high | $V_{CC} = 2.5\text{ V}$ | | 1 | | μs |
| t_{INVL} Receiver positive or negative threshold to $\overline{\text{INVALID}}$ low | $V_{CC} = 2.5\text{ V}$ | | 30 | | μs |
| t_{WU} Receiver or driver edge to driver enabled | $V_{CC} = 2.5\text{ V}$ | | 100 | | μs |
| $t_{AUTOPRDN}$ Receiver or driver edge to driver shutdown | $V_{CC} = 2.5\text{ V}$ | 15 | 30 | 60 | s |

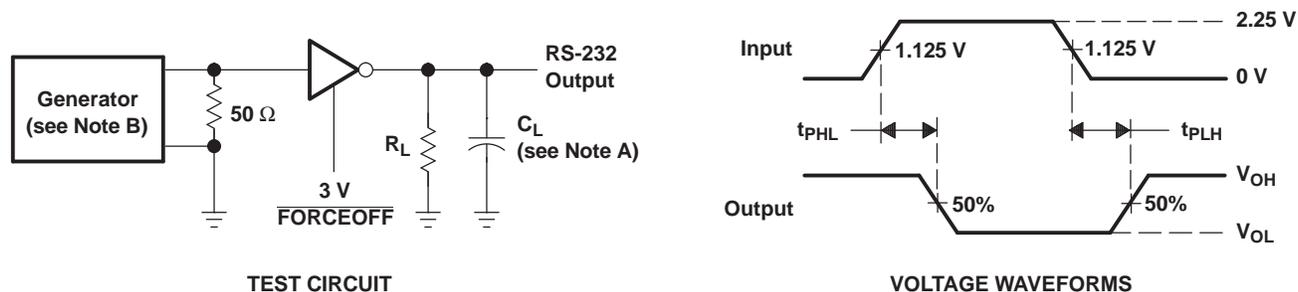
(1) Typical values are at $V_{CC} = 2.5\text{ V}$, $T_A = 25^\circ\text{C}$.

PARAMETER MEASUREMENT INFORMATION



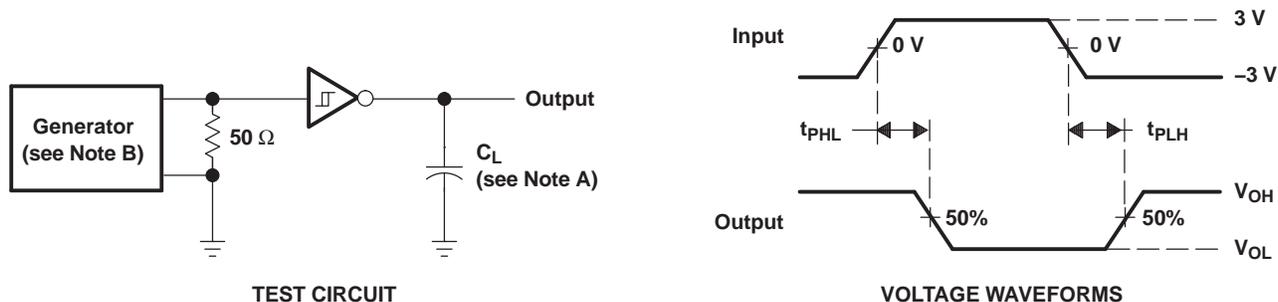
NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 1. Driver Slew Rate



NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

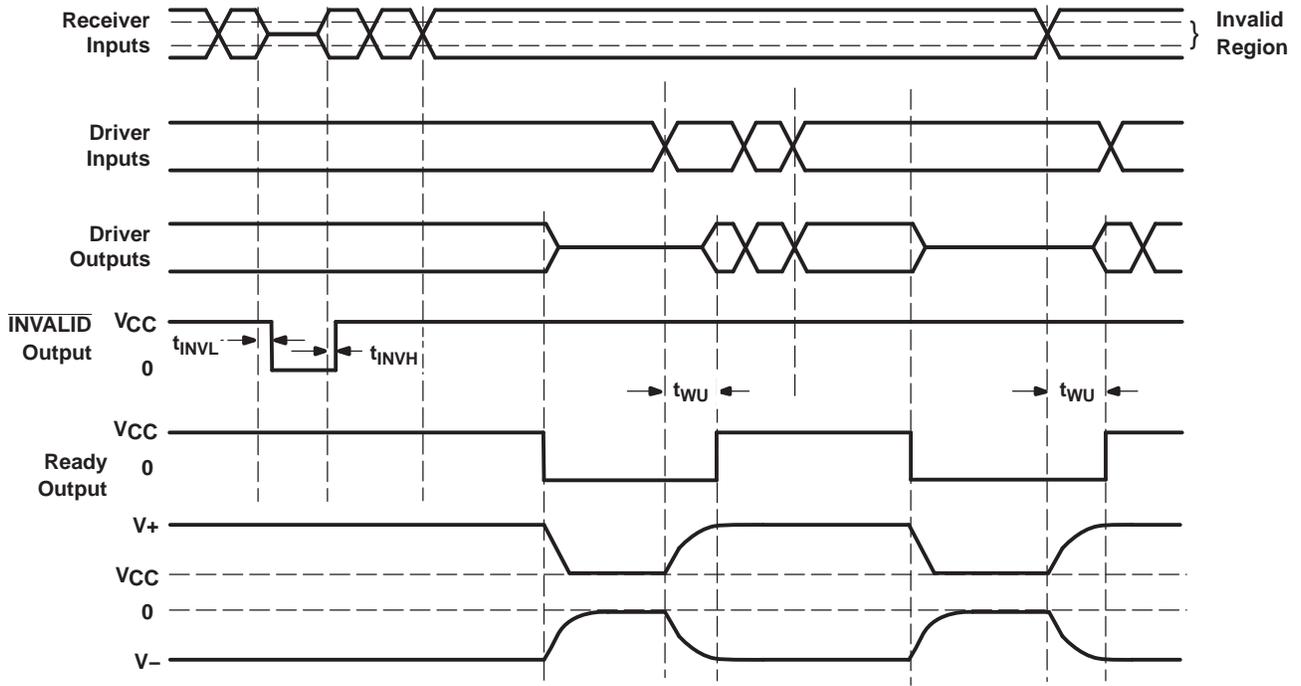
Figure 2. Driver Pulse Skew



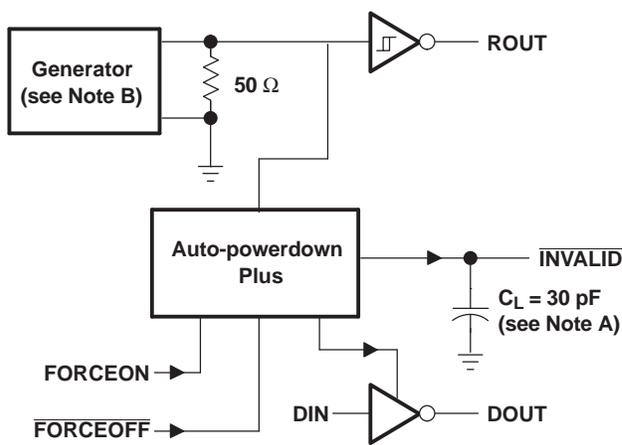
NOTES: A. C_L includes probe and jig capacitance.
 B. The pulse generator has the following characteristics: $Z_O = 50\ \Omega$, 50% duty cycle, $t_r \leq 10\text{ ns}$, $t_f \leq 10\text{ ns}$.

Figure 3. Receiver Propagation Delay Times

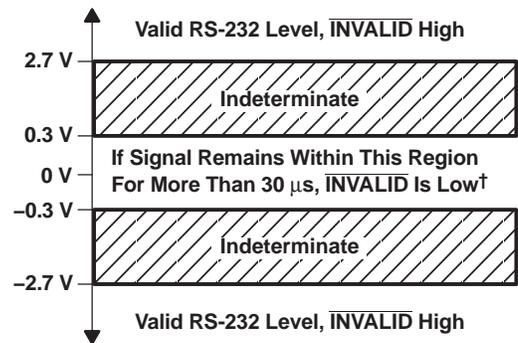
PARAMETER MEASUREMENT INFORMATION (continued)



VOLTAGE WAVEFORMS



TEST CIRCUIT



† Auto-powerdown disables drivers and reduces supply current to 1 μA.

Figure 4. INVALID Propagation Delay Times and Supply Enabling Time

APPLICATION INFORMATION

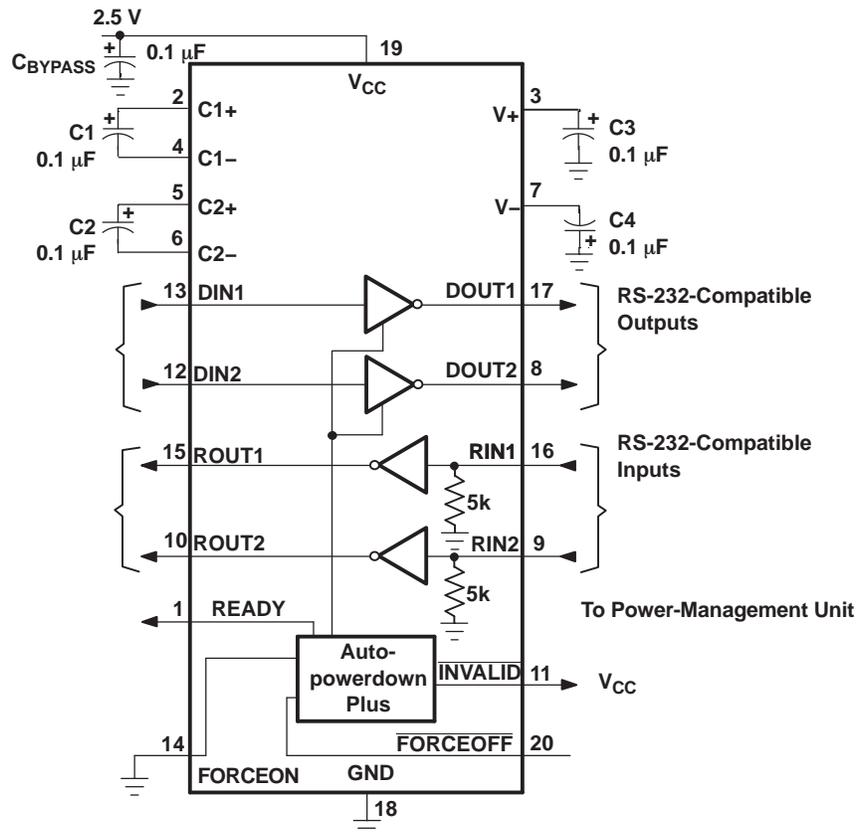


Figure 5. Typical Application Circuit

REVISION HISTORY

| Changes from Revision A (April 2010) to Revision B | Page |
|--|-------------|
| • Updated document to new TI datasheet format - no specification changes. | 1 |
| • Removed Ordering Information table. | 2 |
| • Updated TERMINAL FUNCTIONS table to fix inconsistency. | 3 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|-------------------------|
| TRS3318ECDBR | ACTIVE | SSOP | DB | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | RV18EC | Samples |
| TRS3318ECPW | NRND | TSSOP | PW | 20 | 70 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | RV18EC | |
| TRS3318ECPWR | NRND | TSSOP | PW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | RV18EC | |
| TRS3318EIDBR | NRND | SSOP | DB | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | RV18EI | |
| TRS3318EIPW | NRND | TSSOP | PW | 20 | 70 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | RV18EI | |
| TRS3318EIPWR | ACTIVE | TSSOP | PW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | RV18EI | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

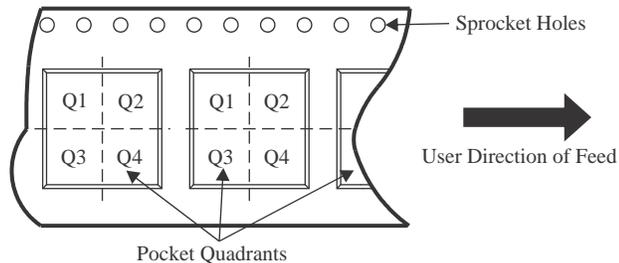
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


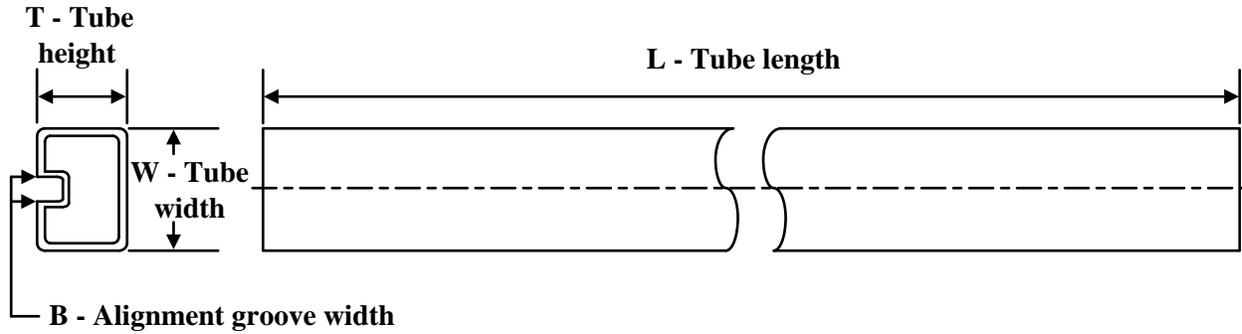
*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TRS3318ECDBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| TRS3318ECPWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| TRS3318EIDBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| TRS3318EIPWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.0 | 1.4 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

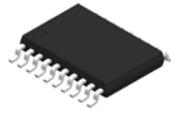
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TRS3318ECDBR | SSOP | DB | 20 | 2000 | 356.0 | 356.0 | 35.0 |
| TRS3318ECPWR | TSSOP | PW | 20 | 2000 | 356.0 | 356.0 | 35.0 |
| TRS3318EIDBR | SSOP | DB | 20 | 2000 | 356.0 | 356.0 | 35.0 |
| TRS3318EIPWR | TSSOP | PW | 20 | 2000 | 356.0 | 356.0 | 35.0 |

TUBE


*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| TRS3318ECPW | PW | TSSOP | 20 | 70 | 530 | 10.2 | 3600 | 3.5 |
| TRS3318EIPW | PW | TSSOP | 20 | 70 | 530 | 10.2 | 3600 | 3.5 |

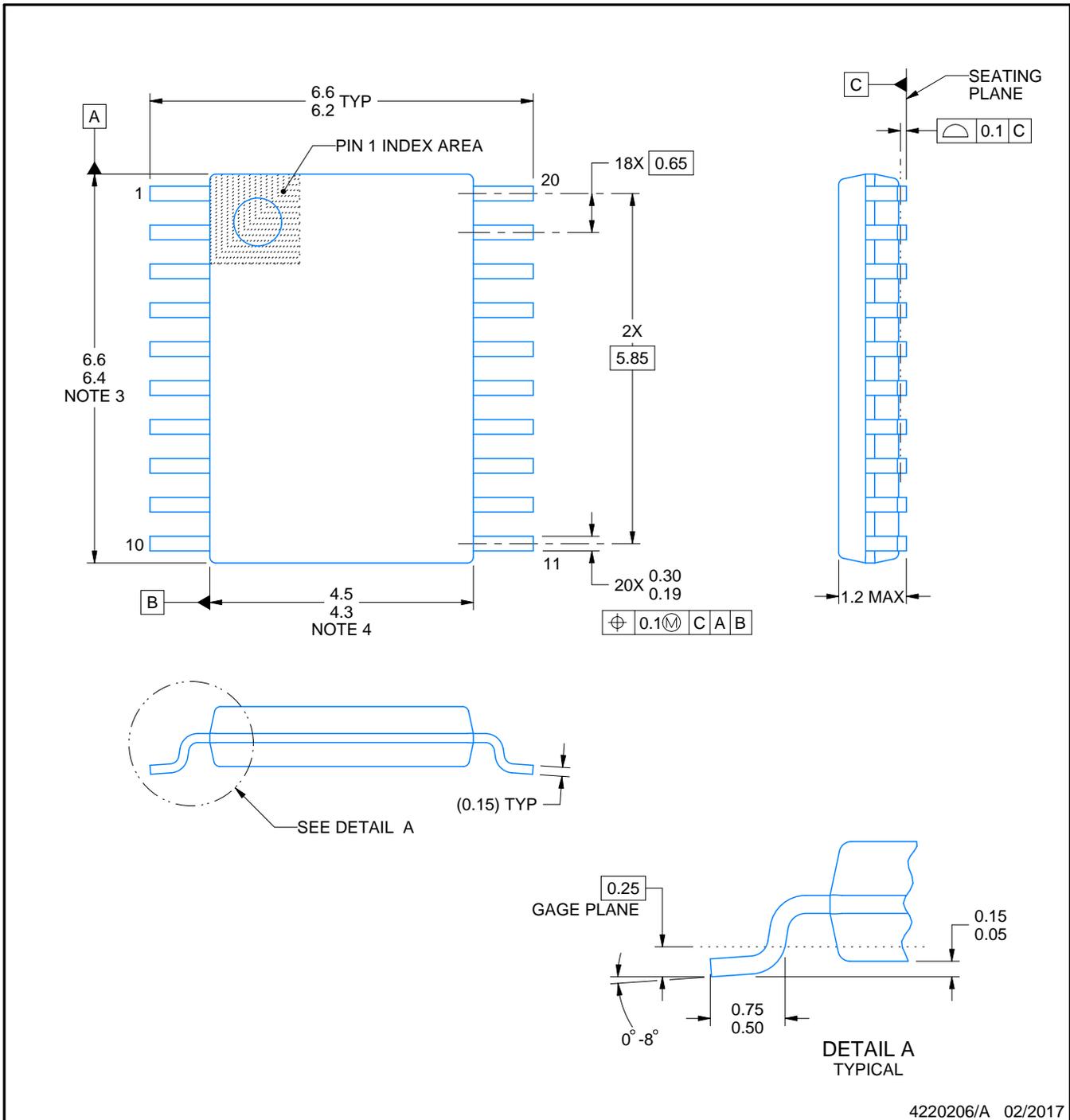
PW0020A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220206/A 02/2017

NOTES:

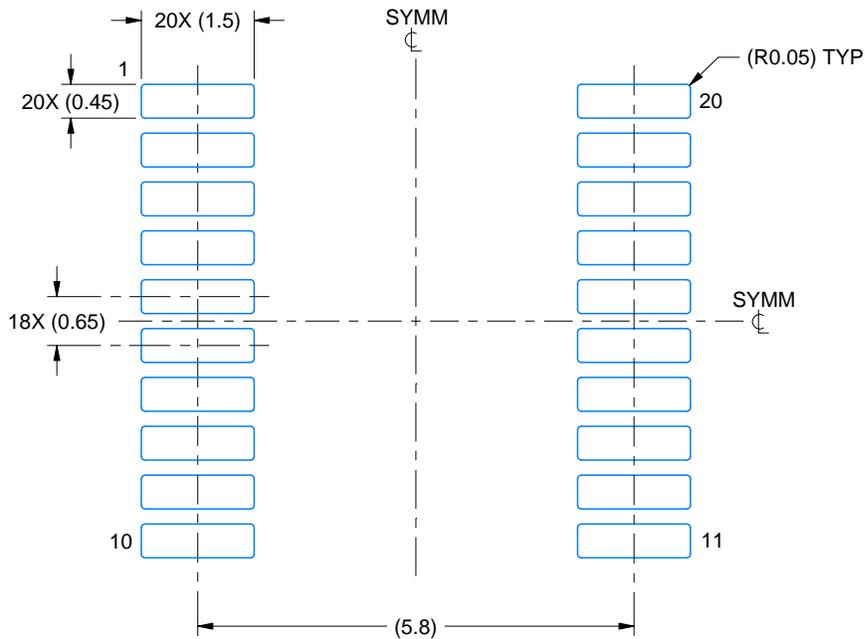
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

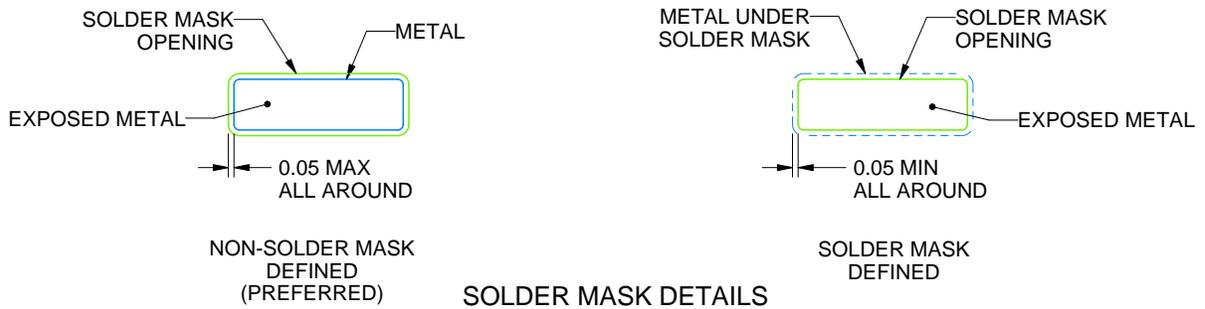
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

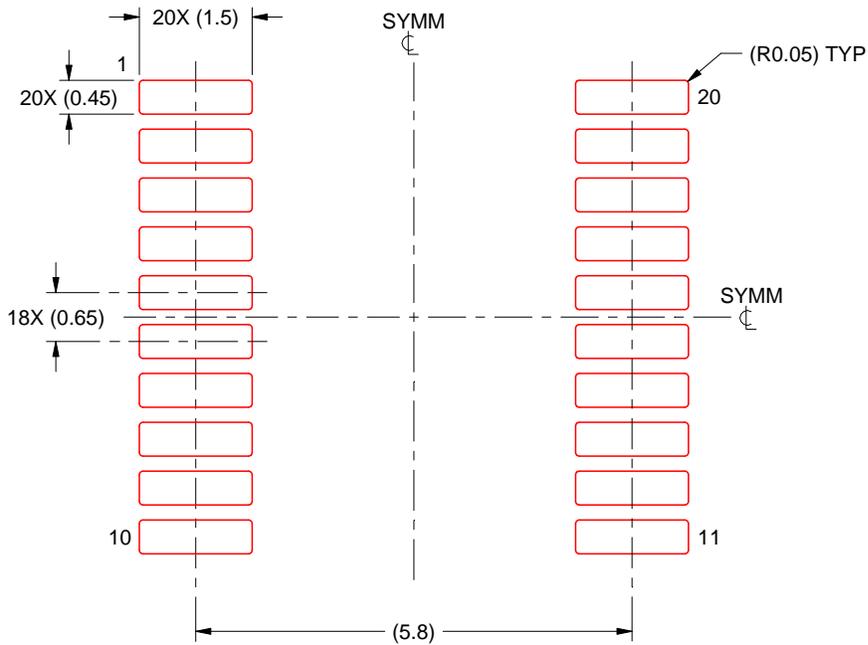
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

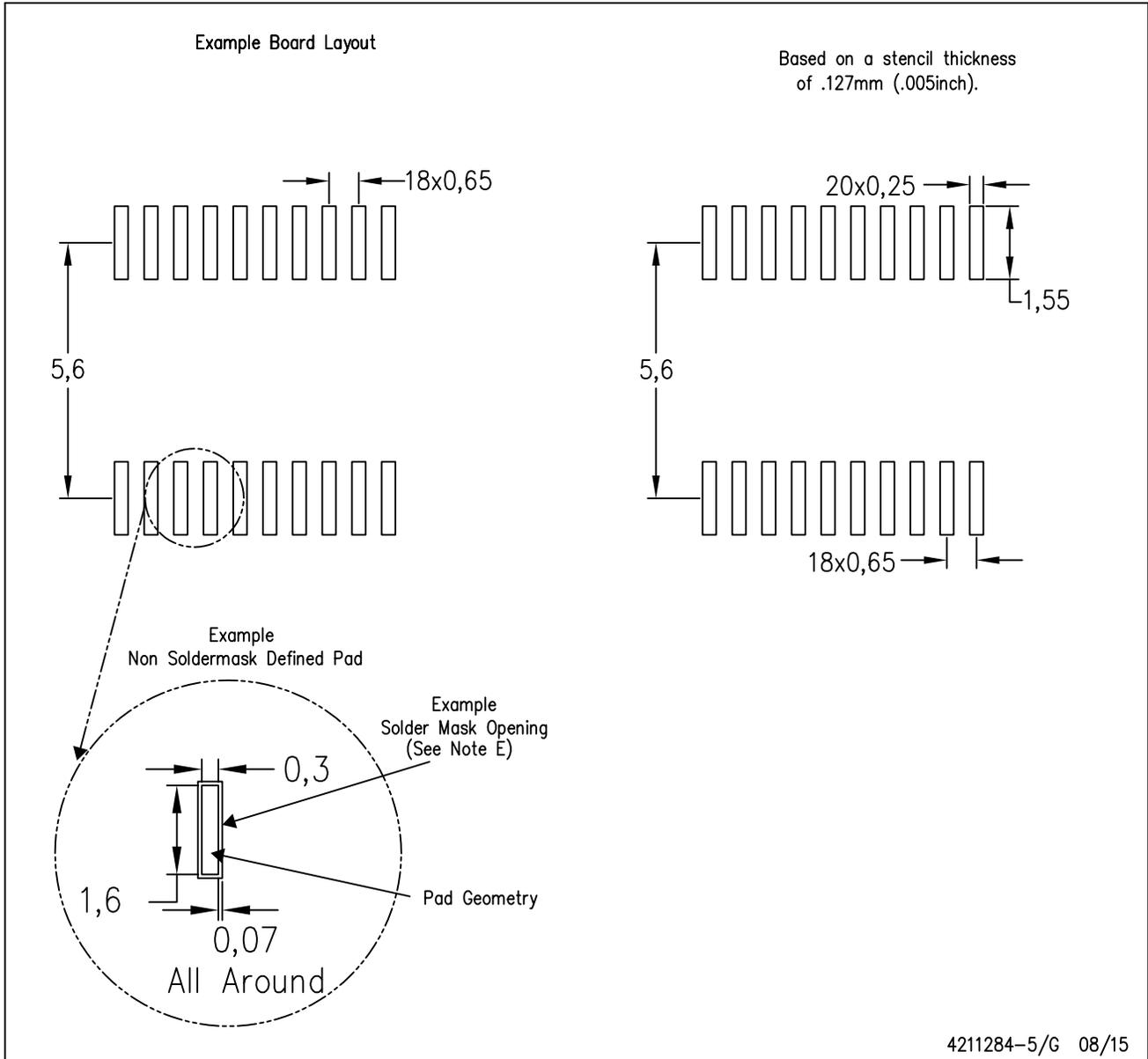
4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

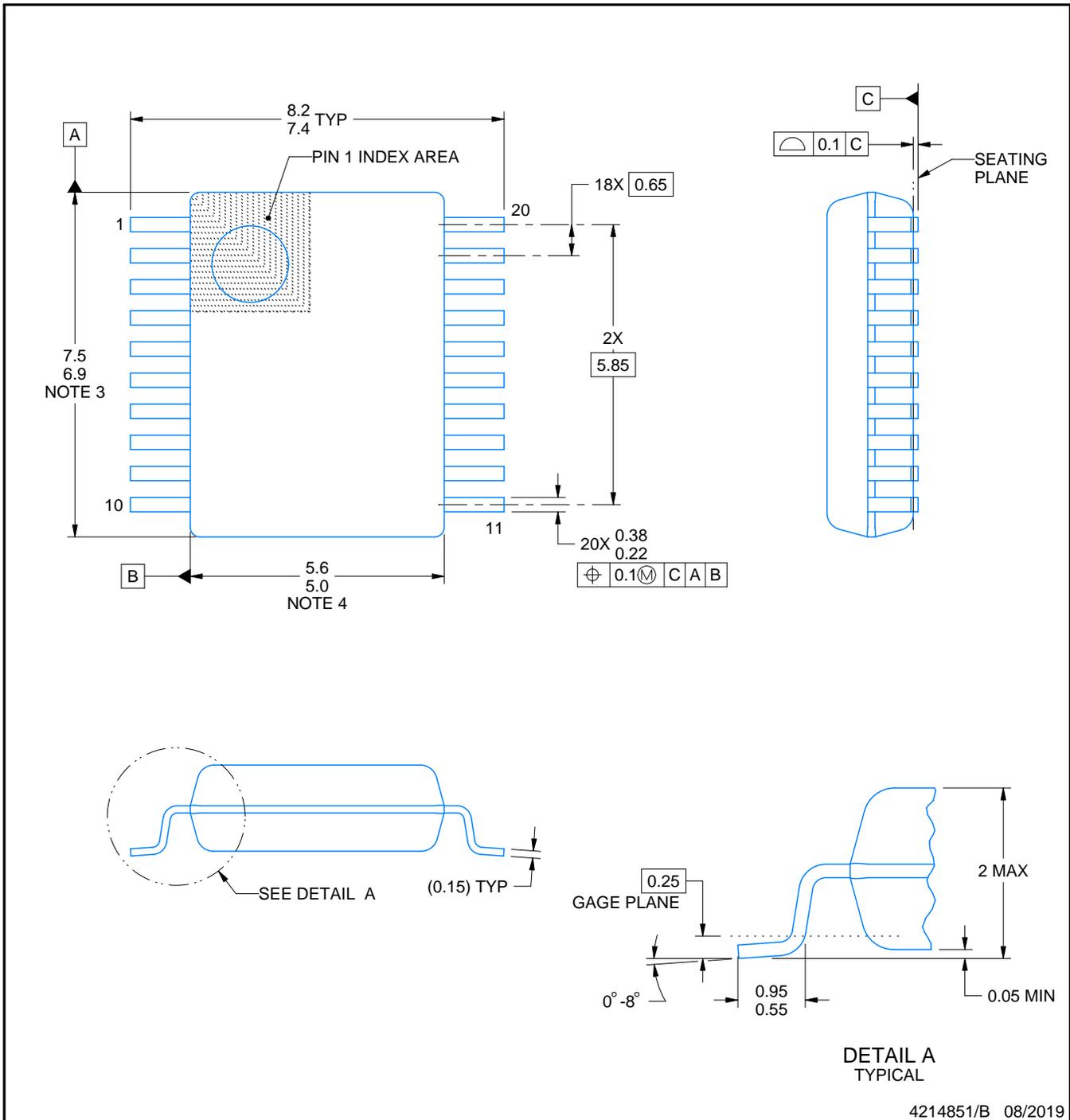
DB0020A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



4214851/B 08/2019

NOTES:

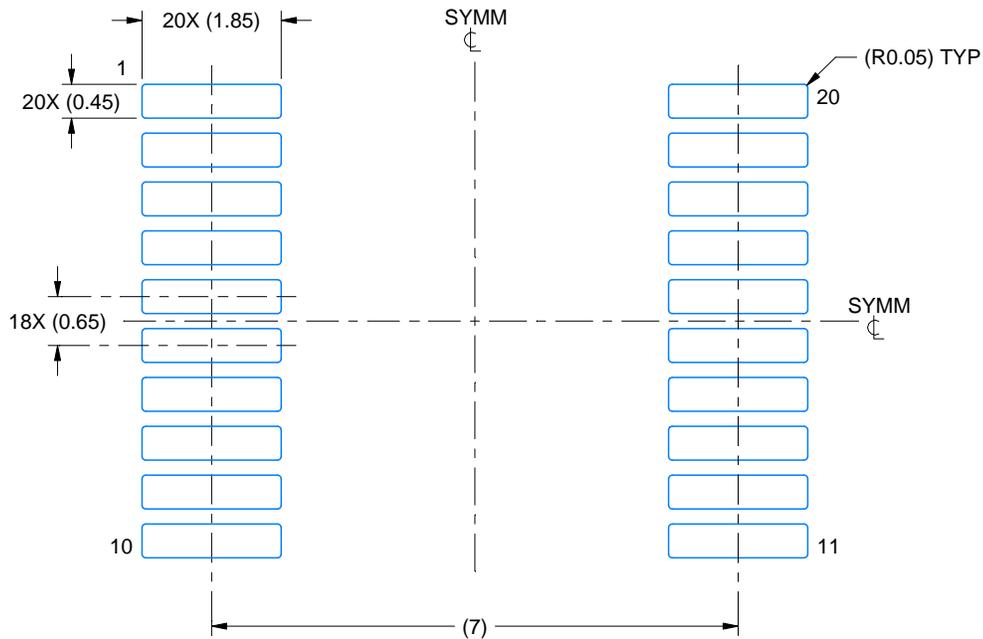
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

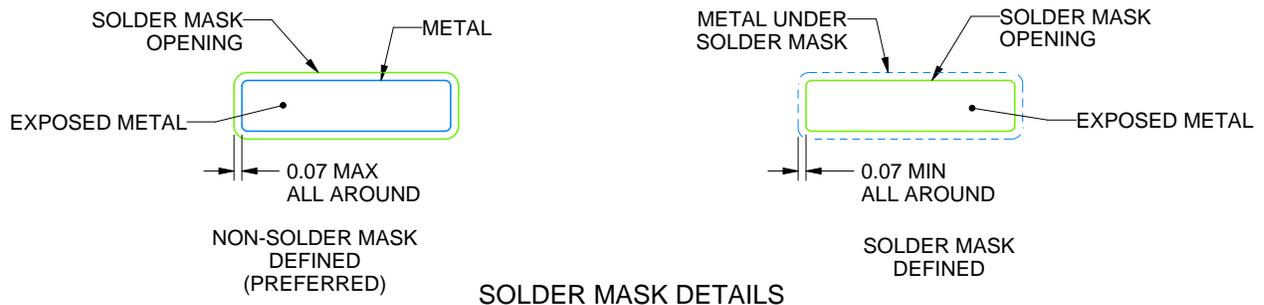
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4214851/B 08/2019

NOTES: (continued)

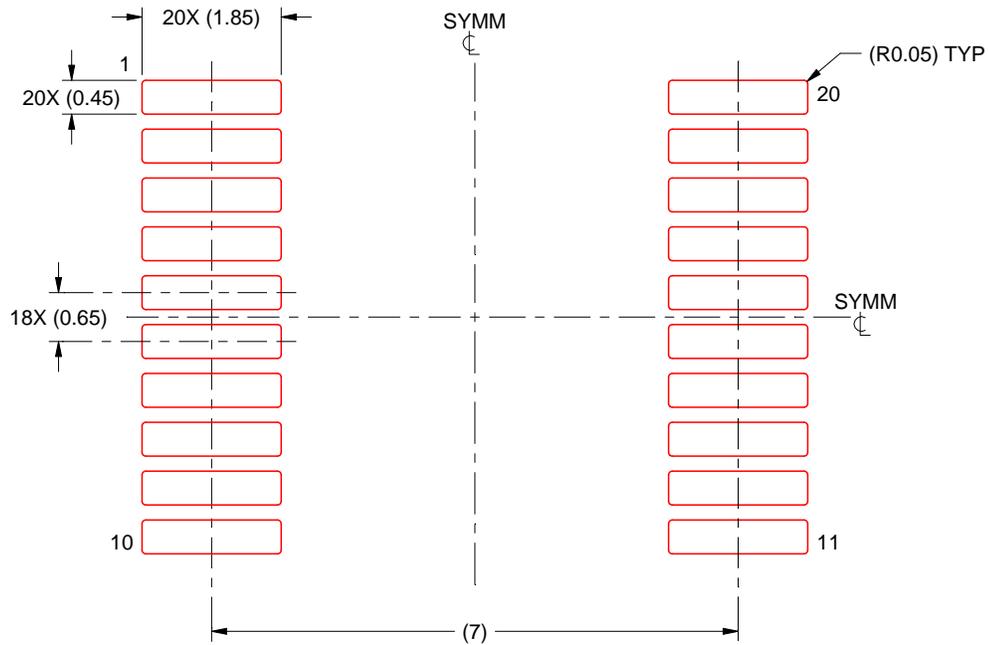
- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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